



BOARD CHARACTERISTICS

Copper Layer Count:	2	Board Thickness:	1.6000 mm
Board overall dimensions:	30.0000 mm x 23.0000 mm		
Min track/spacing:	0.1016 mm / 0.0000 mm	Min hole diameter:	0.2000 mm
Copper Finish:	ENIG	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Direct Printing	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Epoxy	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Epoxy	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Direct Printing	0 mm	Not specified	1	0

Sheet:		
File: TDR1.kicad_pcb		
Title: Tiny TDR – BNC, and SMA connector		
Size: A4	Date: 2024–11–24	Rev: 0.1
KiCad E.D.A. 8.0.6		Id: 1/1